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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re Application of:

Kling, et al.

Application No: 09/974,023

Filed: October 10, 2001

For: *Embedded Capacitor Multi-Chip Modules*

Conf. No.: 7890

Art Unit: 2814

Examiner: Hoai Pham

Atty. Docket: RAK-001.02

### CERTIFICATE OF FIRST CLASS MAILING

I hereby certify that the foregoing documents are being deposited with the United States Postal Service as First Class Mail, postage prepaid, in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313, on this 25<sup>th</sup> day of July, 2003.

John Barretto



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### SUBMISSION OF FORMAL DRAWINGS

Commissioner for Patents  
PO Box 1450  
Alexandria, VA 22313

Attn: Official Draftsperson

Sir:

Applicant hereby submits three (4) sheets of formal drawings containing Figs. 1-7 for the above-referenced application.

Should there be any questions after reviewing this paper, the Examiner is invited to contact the undersigned at 617-832-1175.

Respectfully Submitted,

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Date: July 25, 2003

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